

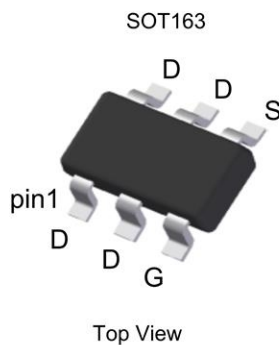
## Product Summary

- 20V/-7 A
- $R_{DS(ON)} = 22m\Omega(Typ.)@V_{GS}=-4.5V$
- $R_{DS(ON)} = 26m\Omega(Typ.)@V_{GS}=-2.5V$

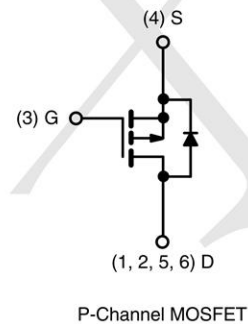
## Application

- Battery Pack
- Portable Devices

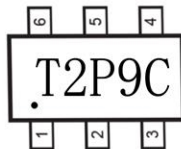
## Package and Pin Configuration



## Circuit diagram



Marking:



## Absolute Maximum Ratings ( $T_A=25^{\circ}C$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	$V_{DS}$	-20	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	$T_C = 25^{\circ}C$	-7
		$T_C = 100^{\circ}C$	-4.9
Pulsed Drain Current <sup>(Note 1)</sup>	$I_{DM}$	-26	A
Total Power Dissipation	$P_{DTOT}$	1.56	W
Operating Junction Temperature	$T_J$	150	$^{\circ}C$
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	- 55 to +150	$^{\circ}C$

## Thermal Characteristic

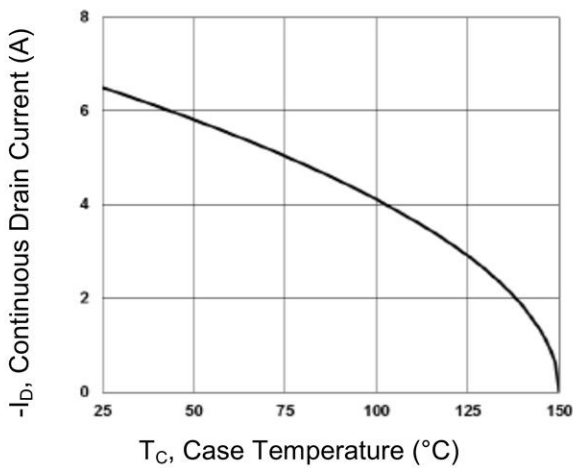
PARAMETER	SYMBOL	LIMIT	UNIT
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	80	$^{\circ}C/W$

### Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

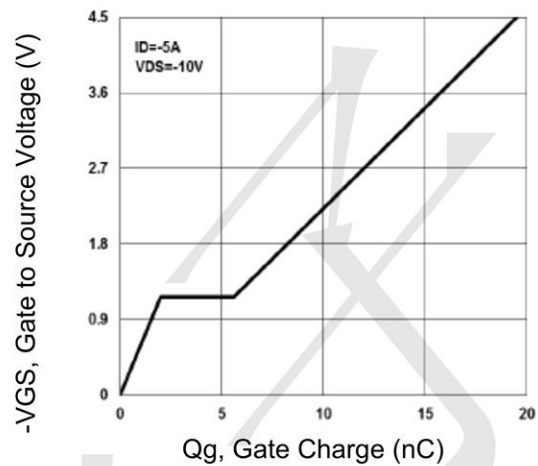
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
<b>Static</b> (Note 2)						
Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	BV <sub>DSS</sub>	-20	--	--	V
Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	V <sub>GS(TH)</sub>	-0.4	--	-1.1	V
Gate Body Leakage	V <sub>GS</sub> = ±12V, V <sub>DS</sub> = 0V	I <sub>GSS</sub>	--	--	±100	nA
Zero Gate Voltage Drain Current	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V	I <sub>DSS</sub>	--	--	-1	μA
	V <sub>DS</sub> = -16V, T <sub>J</sub> = 125°C		--	--	-10	
Drain-Source On-State Resistance	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -5A	R <sub>DS(on)</sub>	--	22	26	mΩ
	V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -4A		--	26	32	
	V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -3A		--	32	40	
Forward Transconductance	V <sub>DS</sub> = -10V, I <sub>S</sub> = -5A	g <sub>fs</sub>	--	15	--	S
<b>Dynamic</b> (Note 3)						
Total Gate Charge	V <sub>DS</sub> = -10V, I <sub>D</sub> = -5A, V <sub>GS</sub> = -4.5V	Q <sub>g</sub>	--	19.5	--	nC
Gate-Source Charge		Q <sub>gs</sub>	--	2	--	
Gate-Drain Charge		Q <sub>gd</sub>	--	3.6	--	
Input Capacitance	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, F = 1.0MHz	C <sub>iss</sub>	--	1670	--	pF
Output Capacitance		C <sub>oss</sub>	--	220	--	
Reverse Transfer Capacitance		C <sub>rss</sub>	--	120	--	
<b>Switching</b>						
Turn-On Delay Time	V <sub>DD</sub> = -10V, I <sub>D</sub> = -1A, V <sub>GS</sub> = -4.5V, R <sub>GEN</sub> = 25Ω	t <sub>d(on)</sub>	--	10.4	--	ns
Turn-On Rise Time		t <sub>r</sub>	--	37.5	--	
Turn-Off Delay Time		t <sub>d(off)</sub>	--	89.1	--	
Turn-Off Fall Time		t <sub>f</sub>	--	24.6	--	
<b>Source-Drain Diode</b>						
Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1A	V <sub>SD</sub>	--	--	-1	V
Continuous Forward Current	Integral reverse diode in the MOSFET	I <sub>S</sub>	--	--	-7	A
Pulse Forward Current		I <sub>SM</sub>	--	--	-26	A

## Typical Electrical and Thermal Characteristics

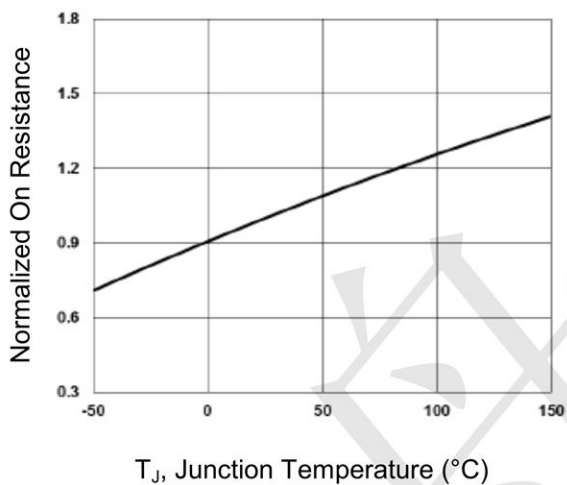
Continuous Drain Current vs.  $T_c$



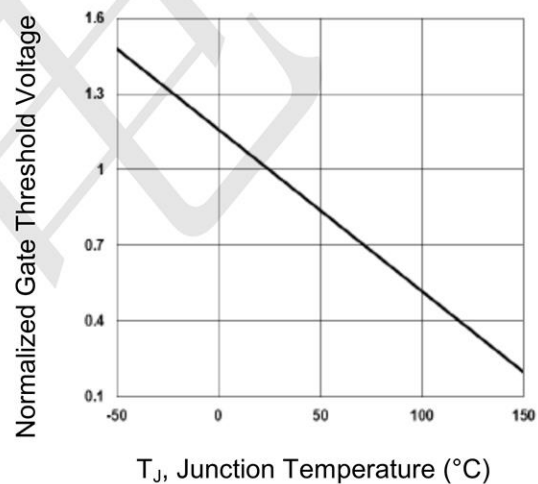
Gate Charge



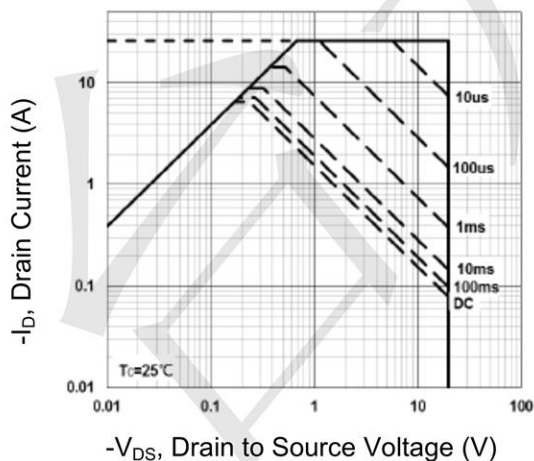
On-Resistance vs. Junction Temperature



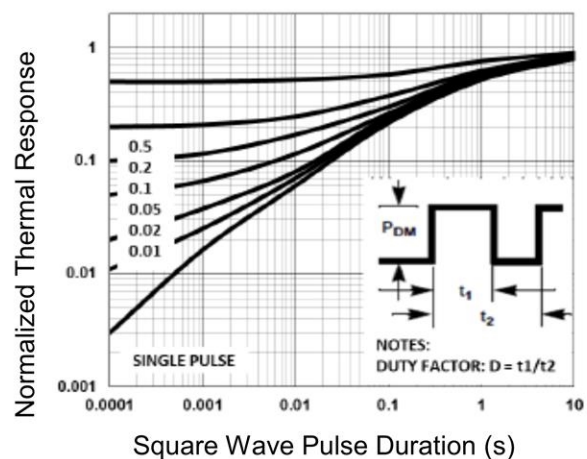
Threshold Voltage vs. Junction Temperature



Maximum Safe Operating Area

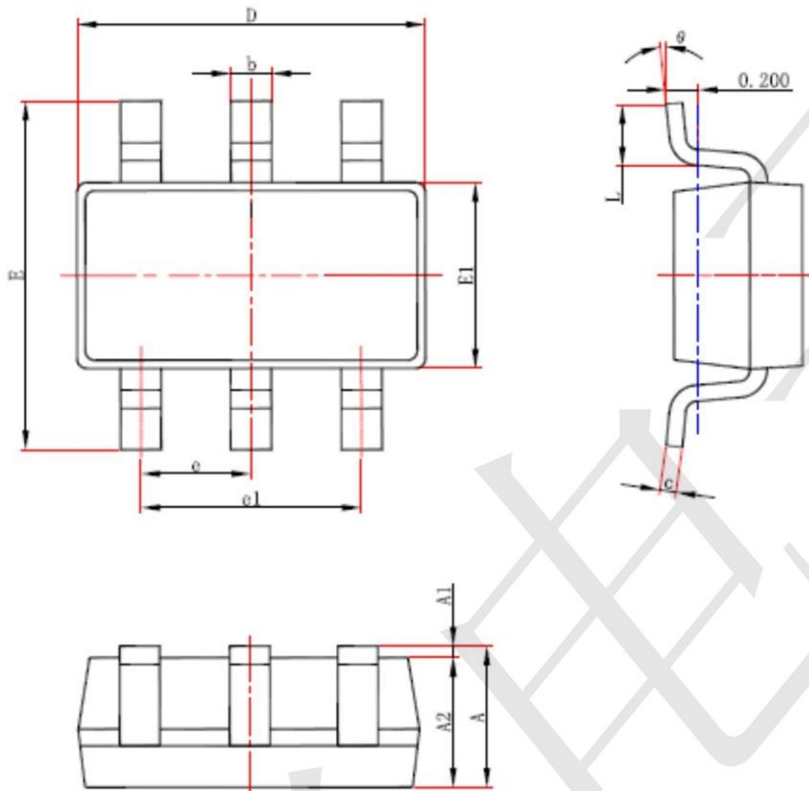


Normalized Thermal Transient Impedance Curve





SOT163 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°